What is claimed is:

- 1. A low radio frequency emissions network device comprising:
 - a chassis; and
 - a layer of foam, having a high insertion loss in the frequency range of electromagnetic
- 5 interference, disposed on at least a portion of a surface of said network device,
 - wherein said layer of foam absorbs at least some of the electromagnetic interference.
 - 2. A low radio frequency emissions network device according to Claim 1 further comprising a network device component disposed in said chassis, said components emitting electromagnetic interference.
 - 3. A low radio frequency emissions network device according to Claim 1 wherein the network device component includes electronic components.
 - 4. A low radio frequency emissions network device according to Claim 1, wherein said network device is a network device operating in the 1-10 GHz range.
 - 5. A low radio frequency emissions network device according to Claim 1, wherein said foam is doped to increase the insertion loss of said foam in the 1-10 GHz range.
 - 6. A low radio frequency emissions network device according to Claim 1, wherein said chassis further comprising a door, wherein said foam is provided at least on a portion of said door of said chassis.
- 7. A low radio frequency emissions network device according to Claim 1, further comprising a Faraday cage.

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- 8. A low radio frequency emissions network device according to Claim 7, wherein said foam is provided outside of said Faraday cage.
- 9. A low radio frequency emissions network device according to Claim 7, wherein said chassis further comprising a door, wherein said foam is provided at least on a portion of said door of said chassis outside said Faraday cage.
- 10. A low radio frequency emissions network device according to Claim 3, wherein said electronic components comprising at least one integrated circuit, wherein said foam is provided at least on top of said integrated circuit.
- 11. A low radio frequency emissions network device according to Claim 3, wherein said electronic components comprising at least one integrated circuit running at a clock speed of 1-10 GHz, wherein said foam is provided at least on top of said integrated circuit running at a clock speed of 1-10 GHz.
- 12. A low radio frequency emissions network device according to Claim 3, wherein said electronic components comprising at least one integrated circuit having a heat sink, wherein said foam is provided at least on top of said heat sink of said integrated circuit.
- 13. A low radio frequency emissions network device according to Claim 3, wherein said electronic components comprising at least one integrated circuit having a heat sink, wherein said foam is provided at least on top of said heat sink of said integrated circuit.
- 25 14. A low radio frequency emissions network device according to Claim 1, wherein said layer of foam is approximately .25 inches in thickness.

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- 15. A low radio frequency emissions network device according to Claim 1, wherein said foam is doped with carbon to increase the insertion loss of said foam in the 1-10 GHz range.
- 16. A low radio frequency emissions network device according to Clam 1, wherein said chassis further comprising a door, said foam being disposed in a first location on at least a portion of said door of said chassis,

wherein said foam in said first location absorbs electromagnetic interference and prevents at least some of the interference from exiting said chassis.

17. A low radio frequency emissions network device according to Claim 2, wherein said foam being disposed in proximity to at least one of said electromagnetic-interference-generating network device components,

wherein said foam absorbs electromagnetic interference and prevents at least some of the interference from exiting said chassis and prevents at least some of the interference from interfering with said network device.

18. A low radio frequency emissions network device according to Claim 16, wherein said foam being disposed in a second location in proximity to at least one of said electromagnetic-interference-generating network device components,

wherein said foam in said second location absorbs electromagnetic interference and prevents at least some of the interference from exiting said chassis and prevents at least some of the interference from interfering with the network device.

19. A low radio frequency emissions network device according to Claim 17, wherein said network device components comprising at least one integrated circuit emitting electromagnetic interference, wherein said foam is disposed directly on top of said integrated circuit.

- 20. A low radio frequency emissions network device according to Claim 17, said network device components comprising at least one integrated circuit emitting electromagnetic interference, said integrated circuit having a heat sink, wherein said foam is disposed directly on top of said heat sink.
- 21. A low radio frequency emissions network device according to Claim 18, said network device components comprising at least one integrated circuit emitting electromagnetic interference, wherein said second location is directly on top of said integrated circuit.
 - 22. A low radio frequency emissions network device according to Claim 18, said network device components comprising at least one integrated circuit emitting electromagnetic interference, said integrated circuit having a heat sink, wherein said second location is directly on top of a heat sink of said integrated circuit.
 - 23. A low electromagnetic interference emissions network device comprising: a chassis, having a door;

electronic components disposed in said chassis, said components including at least one integrated circuit emitting electromagnetic interference in the range of 1-10 GHz; and

a layer of foam having a high insertion loss in the range of 1-10 GHz disposed on at least a portion said door,

wherein at least a portion of the electromagnetic interference is absorbed by the foam and prevented from exiting the chassis.

24. A low electromagnetic interference emissions network device comprising:

a network device component disposed in said network device, said component including at least one integrated circuit emitting electromagnetic interference; and

a layer of foam having a high insertion loss disposed on said network device component, wherein at least a portion of the electromagnetic interference is absorbed by the foam.

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